

# DATA SHEET

## **PCF84C85A**

**Microcontroller with extended I/O**

Product specification  
Supersedes data of May 1994  
File under Integrated Circuits, IC14

1996 Nov 21

**Microcontroller with extended I/O****PCF84C85A****CONTENTS**

1	FEATURES
2	GENERAL DESCRIPTION
3	ORDERING INFORMATION
4	BLOCK DIAGRAM
5	PINNING INFORMATION
5.1	Pinning
5.2	Pin description
6	PARALLEL PORTS
7	INSTRUCTION SET
8	SUMMARY OF DERIVATIVE PORTS AND REGISTERS
9	ROM MASK OPTIONS
10	HANDLING
11	LIMITING VALUES
12	DC CHARACTERISTICS
13	AC CHARACTERISTICS
13.1	I <sup>2</sup> C-bus interface characteristics
14	PACKAGE OUTLINES
15	SOLDERING
15.1	Introduction
15.2	DIP
15.2.1	Soldering by dipping or by wave
15.2.2	Repairing soldered joints
15.3	SO and VSO
15.3.1	Reflow soldering
15.3.2	Wave soldering
15.3.3	Repairing soldered joints
16	DEFINITIONS
17	LIFE SUPPORT APPLICATIONS
18	PURCHASE OF PHILIPS I <sup>2</sup> C COMPONENTS



## Microcontroller with extended I/O

## PCF84C85A

**1 FEATURES**

- 8-bit CPU, ROM, RAM, I/O in a single 40-lead package
- 8 kbytes ROM
- 256 bytes RAM
- I<sup>2</sup>C-bus interface with multi-master capability
- Over 100 instructions (based on MAB8048) all of 1 or 2 cycles
- 32 quasi-bidirectional I/O port lines
- 8-bit programmable timer/event counter 1
- Three single-level vectored interrupts:
  - external
  - 8-bit programmable timer/event counter 1
  - I<sup>2</sup>C-bus
- Two test inputs, one of which also serves as the external interrupt input
- Stop and Idle modes
- Logic supply voltage:  $V_{DD} = 2.5$  to  $5.5$  V
- Clock frequency: 1 to 16 MHz
- Operating temperature:  $-40$  to  $+85$  °C
- Manufactured in silicon gate CMOS process.

**3 ORDERING INFORMATION** (see note 1)

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PCF84C85AP	DIP40	plastic dual in-line package; 40 leads (600 mil)	SOT 129-1
PCF84C85AT	VSO40	plastic very small outline package; 40 leads	SOT 158-1

**Note**

1. Please refer to the Order Entry Form (OEF) for this device for the full type number to use when ordering. This type number will also specify the required program and the ROM mask options.

**2 GENERAL DESCRIPTION**

This data sheet details the specific properties of the PCF84C85A. The shared properties of the PCF84CxxxA family of microcontrollers are described in the "PCD84xxxA family" data sheet which should be read in conjunction with this publication.

The PCF84C85A is a general purpose CMOS microcontroller with emphasis on input/output. It provides 32 I/O port lines, 8 kbytes of program memory and 256 bytes of RAM. In addition to the 32 I/O port lines, the microcontroller provides an on-chip I<sup>2</sup>C-bus interface. This two-line serial bus extends the microcontroller's capabilities when implemented with the powerful I<sup>2</sup>C-bus peripherals. These include LCD drivers, telecom circuits, AD/DA converters, clock/calendar circuits, EEPROM and RAM and are listed in "Data Handbook IC12, I<sup>2</sup>C Peripherals".

The instruction set is based on that of the MAB8048 and is a sub-set of that listed in the "PCF84CXXXA family" data sheet.

Microcontroller with extended I/O

PCF84C85A

4 BLOCK DIAGRAM

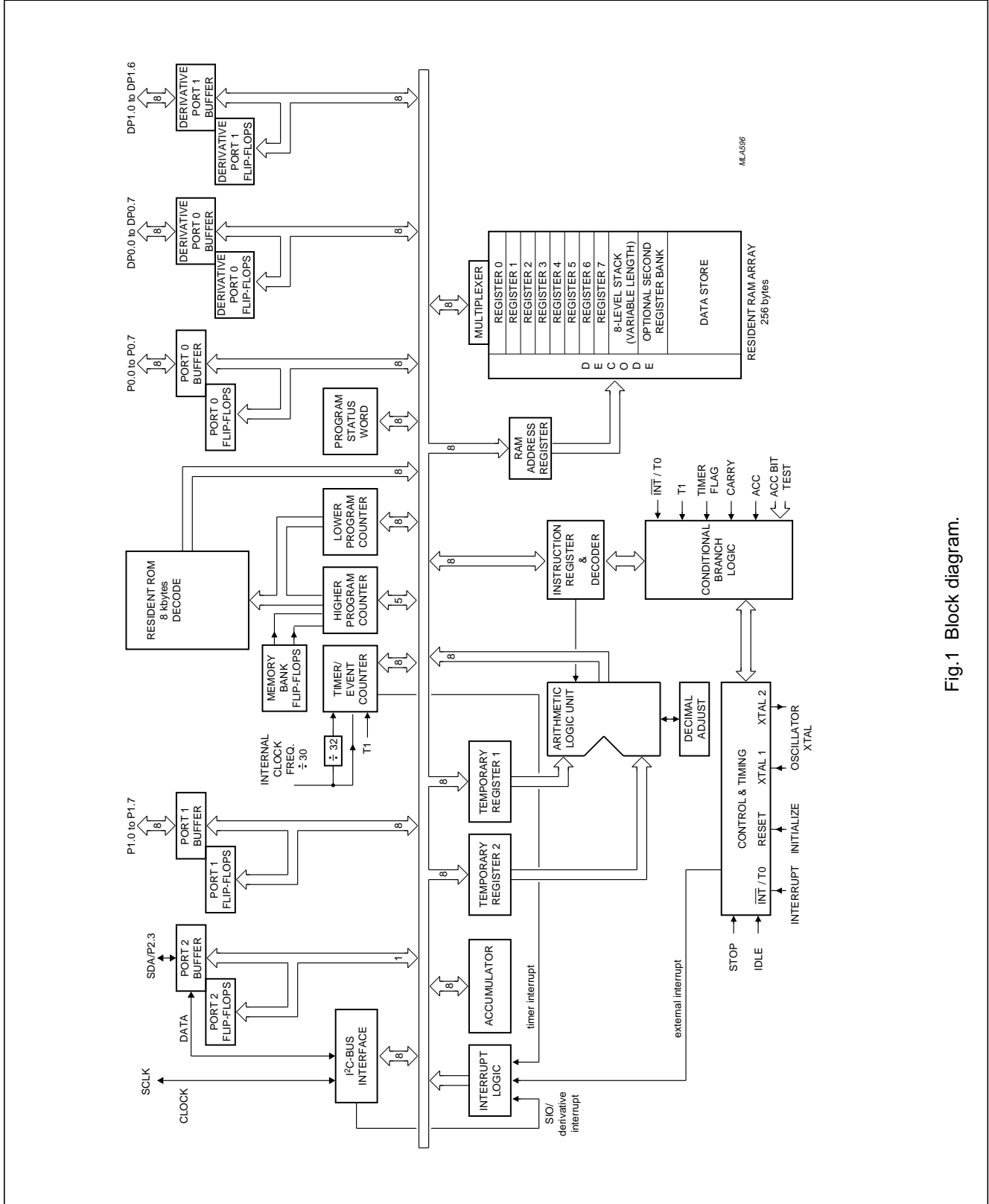


Fig.1 Block diagram.

Microcontroller with extended I/O

PCF84C85A

5 PINNING INFORMATION

5.1 Pinning

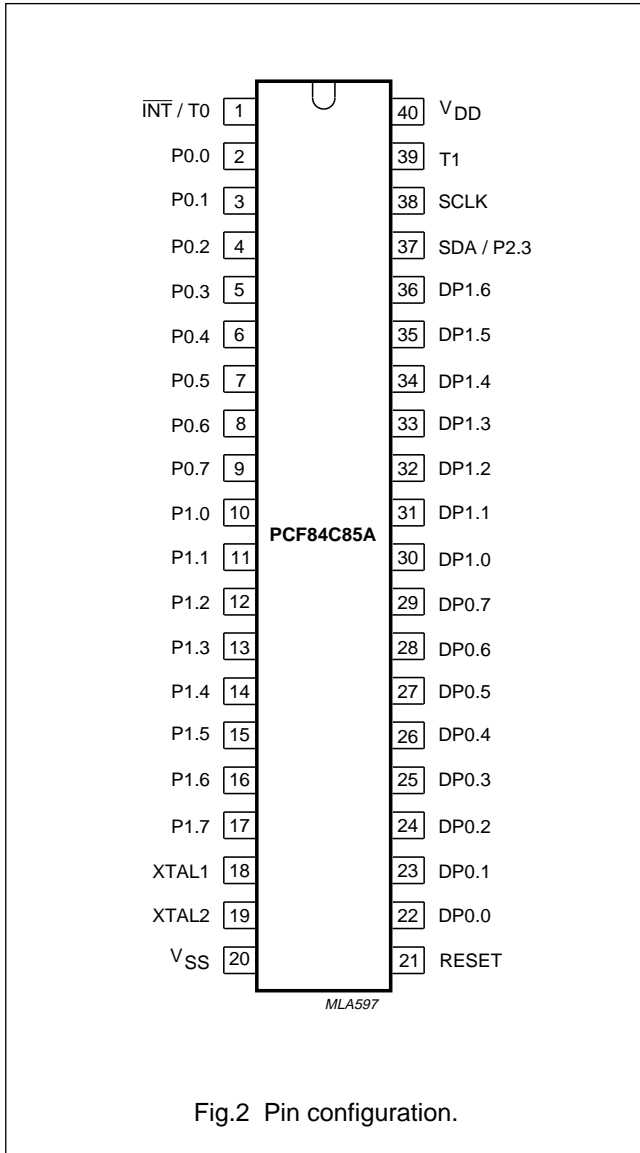


Fig.2 Pin configuration.

5.2 Pin description

Table 1 DIP40 and VSO40 packages.

SYMBOL	PIN	TYPE	DESCRIPTION
INT/T0	1	I	Interrupt/Test 0
P0.0 to P0.7	2 to 9	I/O	8 bits of Port 0: 8-bit quasi-bidirectional I/O port
P1.0 to P1.7	10 to 17	I/O	8 bits of Port 1: 8-bit quasi-bidirectional I/O port
XTAL1	18	I	XTAL input: crystal oscillator/external clock input
XTAL2	19	O	XTAL output: crystal oscillator output
V <sub>SS</sub>	20	P	ground
RESET	21	I	Reset input
DP0.0 to DP0.7	22 to 29	I/O	Derivative Port 0: quasi-bidirectional I/O port (8-bit)
DP1.0 to DP1.6	30 to 36	I/O	Derivative Port 1: quasi-bidirectional I/O lines (7-bit)
SDA/P2.3	37	I/O	bidirectional data line of the I <sup>2</sup> C-bus interface; or Port 2 quasi-bidirectional I/O port (1 bit only)
SCLK	38	I/O	bidirectional clock line of the I <sup>2</sup> C-bus interface
T1	39	I	Test 1: count input of 8-bit timer/event counter 1
V <sub>DD</sub>	40	P	positive supply

6 PARALLEL PORTS

Of the standard quasi-bidirectional I/O ports, Port 2 is incomplete, providing only line SDA/P2.3 that is shared with the I<sup>2</sup>C-bus interface. In addition to the standard ports, two derivative I/O ports are available:

- Derivative Port of 8 lines (DP0.0 to DP0.7)
- Derivative Port of 7 lines (DP1.0 to DP1.6).

Missing bits of incomplete ports, i.e. P2.0 to P2.2 and DP1.7, are fixed at zero in the corresponding registers.

7 INSTRUCTION SET

See "PCF84CXXXA family" data sheet for a complete description of the instruction set.

## Microcontroller with extended I/O

## PCF84C85A

## 8 SUMMARY OF DERIVATIVE PORTS AND REGISTERS

Table 2 Derivative Ports.

DERIVATIVE ADDRESS	TYPE	REGISTER MNEMONIC	DESCRIPTION
00H	R	DP0L	Derivative Port 0 lines
01H	R	DP1L	Derivative Port 1 lines
02H	R/W	DP0FF	Derivative Port 0 flip-flops
03H	R/W	DP1FF	Derivative Port 1 flip-flops
04H	–	–	

Table 3 Derivative Registers.

REGISTER MNEMONIC	7	6	5	4	3	2	1	0
DP0L	D0.7	D0.6	D0.5	D0.4	D0.3	D0.2	D0.1	D0.0
DP1L	0	D1.6	D1.5	D1.4	D1.3	D1.2	D1.1	D1.0
DP0FF	F0.7	F0.6	F0.5	F0.4	F0.3	F0.2	F0.1	F0.0
DP1FF	0	F1.6	F1.5	F1.4	F1.3	F1.2	F1.1	F1.0

## 9 ROM MASK OPTIONS

ROM CODE	OPTION		
<b>Program/data</b>	Any mix of instructions and data up to ROM size of 8 kbytes.		
<b>Port Output</b>			
P0.0 to P0.7	standard	open-drain	push-pull
P1.0 to P1.7	standard	open-drain	push-pull
SDA/P2.3	–	open-drain	–
DP0.0 to DP0.7	standard	open-drain	push-pull
DP1.0 to DP1.7	standard	open-drain	push-pull
<b>Port State after reset</b>			
P0.0 to P0.7	set	reset	–
P1.0 to P1.7	set	reset	–
SDA/P2.3	set	–	–
DP1.0 to DP1.7	set	reset	–
DP2.0 to DP2.2	set	reset	–
<b>Oscillator</b>			
Transconductance	LOW (g <sub>mL</sub> )	MEDIUM (g <sub>mM</sub> )	HIGH (g <sub>mH</sub> )

## Microcontroller with extended I/O

## PCF84C85A

**10 HANDLING**

Inputs and outputs are protected against electrostatic discharge in normal handling. However, it is good practice to take normal precautions appropriate to handling MOS devices. See "Data Handbook IC14, Section: Handling MOS devices".

**11 LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
$V_{DD}$	supply voltage	-0.5	+7	V
$V_I$	all input voltages	-0.5	$V_{DD} + 0.5$	V
$I_I$	DC input current	-10	+10	mA
$I_O$	DC output current	-10	+10	mA
$P_{tot}$	total power dissipation	-	125	mW
$P_O$	power dissipation per output	-	30	mW
$I_{SS}$	ground supply current ( $V_{SS}$ )	-50	+50	mA
$T_{stg}$	storage temperature range	-65	+150	°C
$T_j$	operating junction temperature	-	90	°C

## Microcontroller with extended I/O

## PCF84C85A

**12 DC CHARACTERISTICS**

$V_{DD} = 2.5$  to  $5.5$  V;  $V_{SS} = 0$  V;  $T_{amb} = -40$  to  $+85$  °C; all voltages with respect to  $V_{SS}$ ; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{DD}$	operating supply voltage	see Fig. 3	2.5	–	5.5	V
$I_{DD}$	operating supply current	note 1; see Figs 4 and 5 $V_{DD} = 3$ V; $f_{xtal} = 3.58$ MHz ( $g_{mL}$ ) $V_{DD} = 5$ V; $f_{xtal} = 10$ MHz ( $g_{mL}$ ) $V_{DD} = 5$ V; $f_{xtal} = 16$ MHz ( $g_{mM}$ ) $V_{DD} = 5$ V; $f_{xtal} = 16$ MHz ( $g_{mH}$ )	– – – –	0.3 1.1 1.7 2.5	0.6 3.0 5.0 6.0	mA mA mA mA
$I_{DD(idle)}$	supply current (Idle mode)	note 1; see Figs 6 and 7 $V_{DD} = 3$ V; $f_{xtal} = 3.58$ MHz ( $g_{mL}$ ) $V_{DD} = 5$ V; $f_{xtal} = 10$ MHz ( $g_{mL}$ ) $V_{DD} = 5$ V; $f_{xtal} = 16$ MHz ( $g_{mM}$ ) $V_{DD} = 5$ V; $f_{xtal} = 16$ MHz ( $g_{mH}$ )	– – – –	0.2 0.8 1.2 1.7	0.4 1.6 4.0 5.0	mA mA mA mA
$I_{DD(stp)}$	supply current (Stop mode)	$V_{DD} = 2.5$ V; notes 1 and 2; see Fig.8	–	1.2	10	µA
<b>Inputs</b>						
$V_{IL}$	LOW level input voltage		0	–	$0.3V_{DD}$	V
$V_{IH}$	HIGH level input voltage		$0.7V_{DD}$	–	$V_{DD}$	V
$I_{LI}$	input leakage current	$V_{SS} \leq V_I \leq V_{DD}$	–1	–	+1	µA
<b>Outputs</b>						
$I_{OL}$	LOW level output sink current; except SDA/P2.3 and SCLK	$V_{DD} = 5$ V; $V_O = 0.4$ V; see Fig.9	1.6	12	–	mA
$I_{OL2}$	LOW level output sink current; SDA/P2.3 and SCLK	$V_{DD} = 5$ V; $V_O = 0.4$ V; see Fig.10	3.0	12	–	mA
$I_{OH}$	HIGH level pull-up output source current	$V_{DD} = 5$ V; $V_O = 3.5$ V; see Fig.11	–40	–100	–	µA
		$V_{DD} = 5$ V; $V_O = 0$ V; see Fig.11	–	–140	–400	µA
$I_{OH1}$	HIGH level push-pull output source current	$V_{DD} = 5$ V; $V_O = 4.6$ V; see Fig.12	–1.6	–7	–	mA
<b>Oscillator</b> (see Fig.13)						
$g_{mL}$	LOW transconductance	$V_{DD} = 5$ V	0.2	0.4	1.0	mS
$g_{mM}$	MEDIUM transconductance	$V_{DD} = 5$ V	0.9	1.6	3.2	mS
$g_{mH}$	HIGH transconductance	$V_{DD} = 5$ V	3.0	4.5	9.0	mS
$R_F$	feedback resistor		0.3	1.0	3.0	MΩ

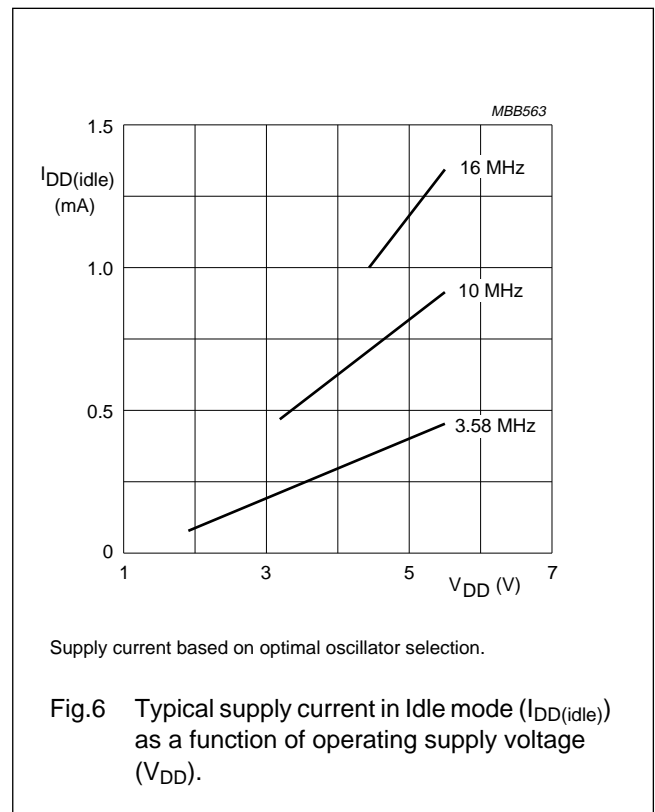
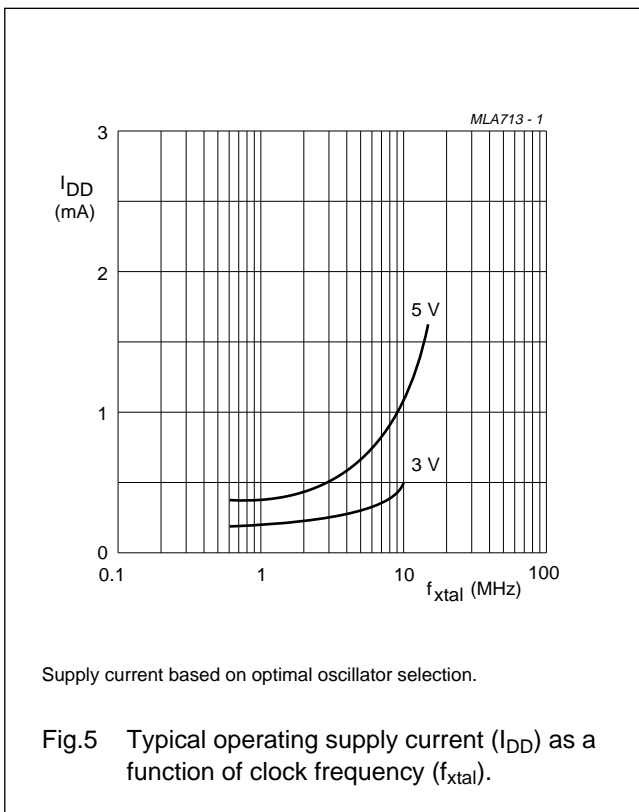
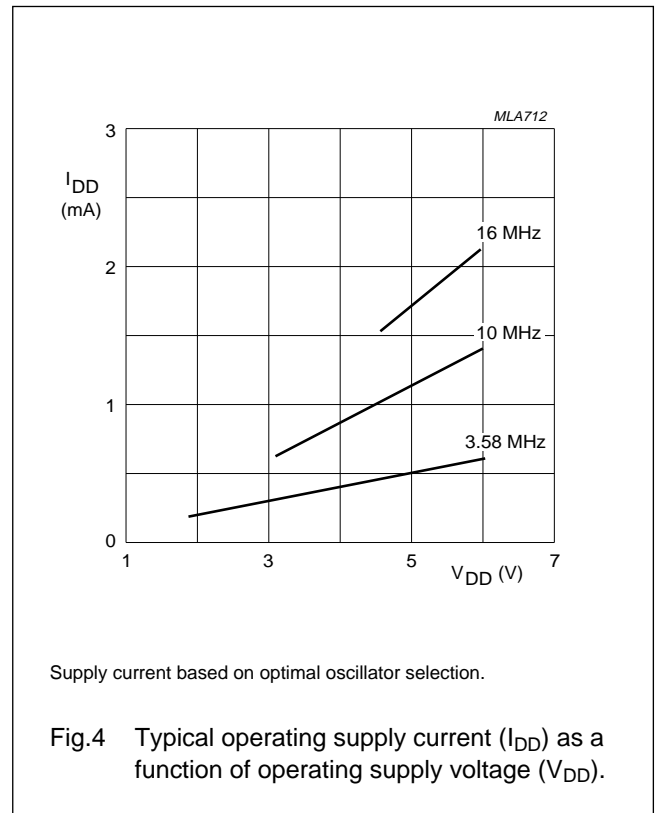
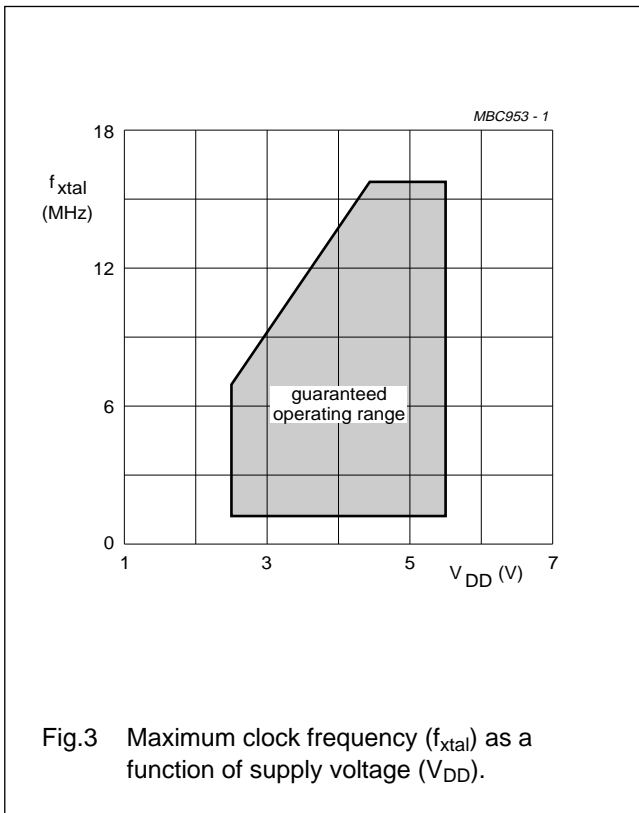
**Notes**

- $V_{IL} = V_{SS}$ ;  $V_{IH} = V_{DD}$ ; open drain outputs connected to  $V_{SS}$ ; all other outputs, including XTAL2, open (typical values at 25 °C with crystal connected between XTAL1 and XTAL2).
- $V_{IL} = V_{SS}$ ;  $V_{IH} = V_{DD}$ ; RESET and T1 at  $V_{SS}$ ;  $\overline{INT}/T0$  at  $V_{DD}$ ; crystal connected between XTAL1 and XTAL2; open drain outputs connected to  $V_{SS}$ ; all other outputs open.



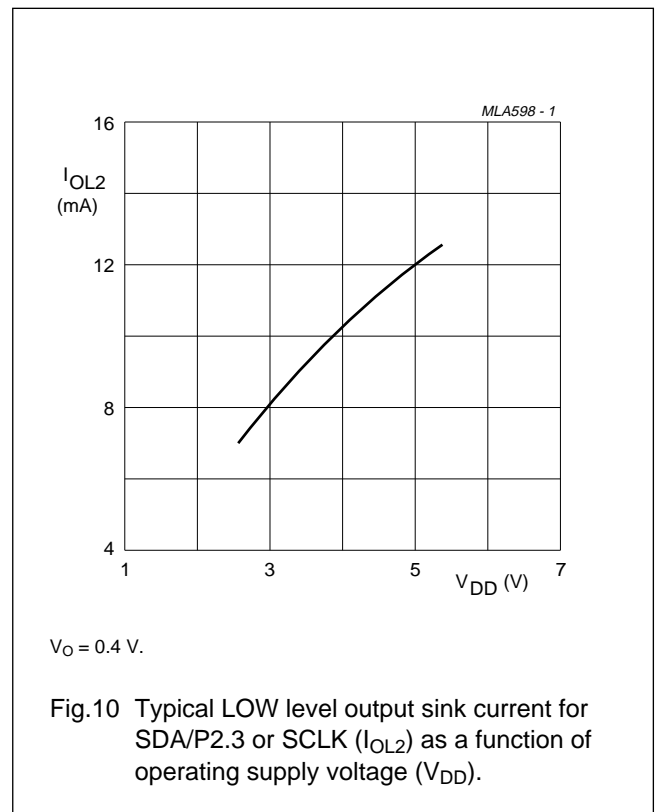
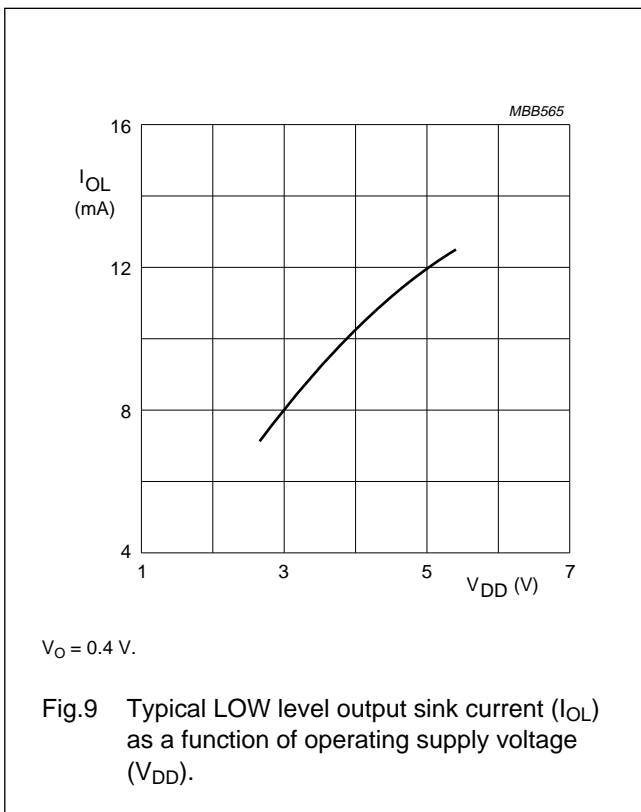
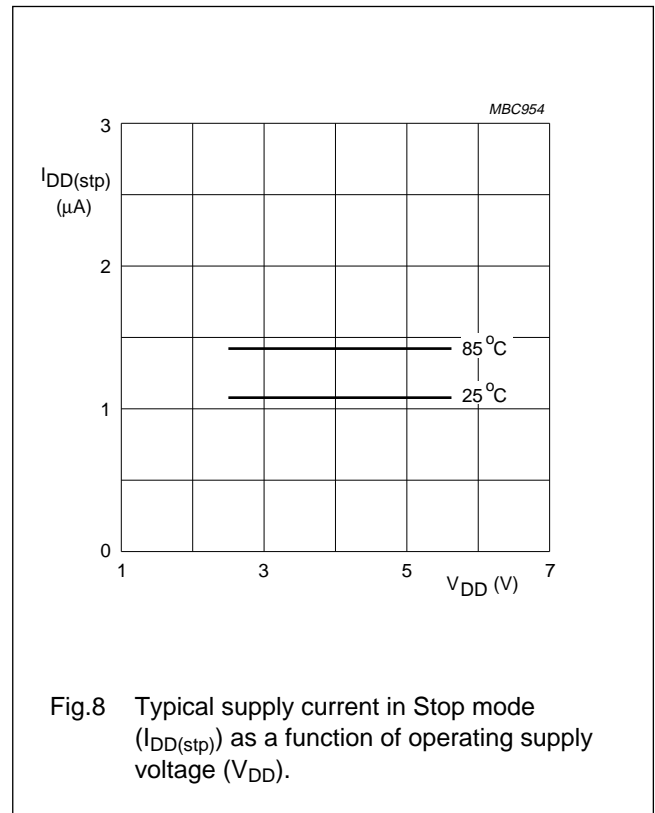
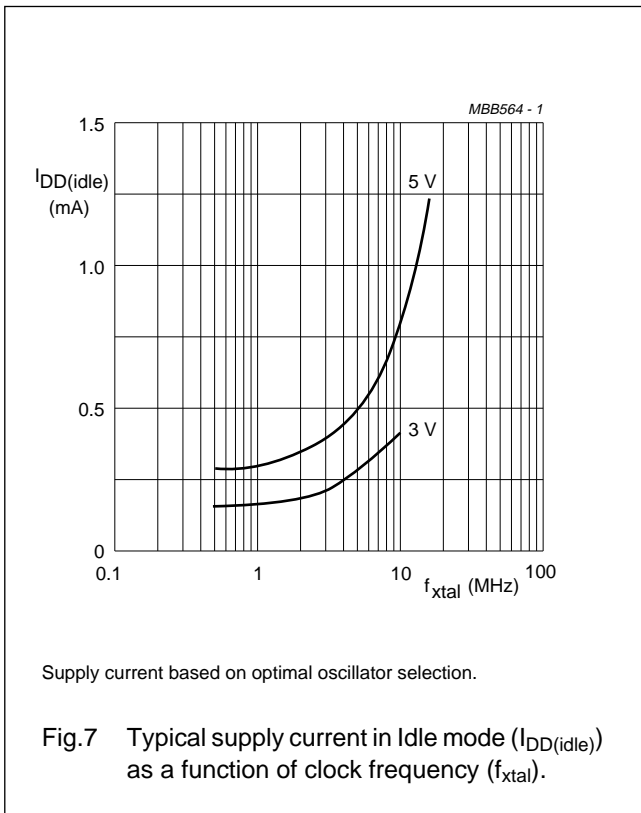
Microcontroller with extended I/O

PCF84C85A



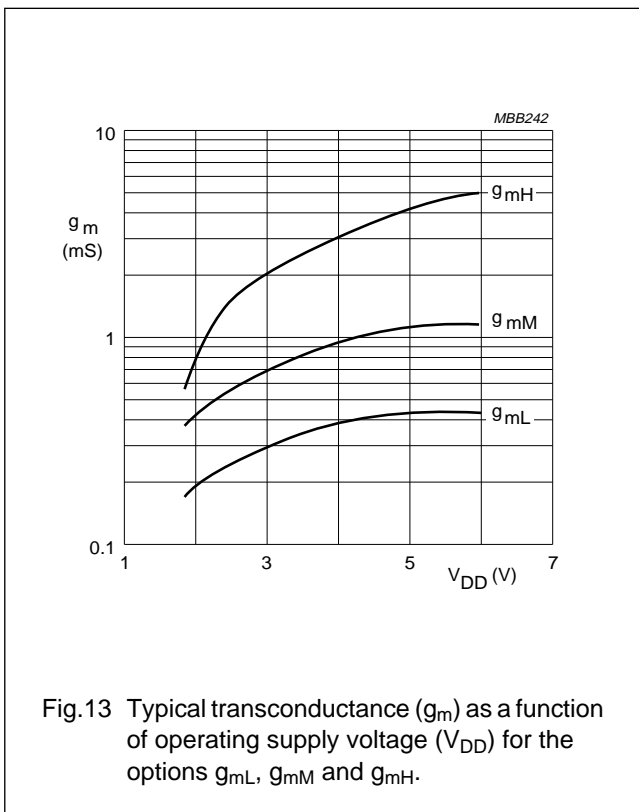
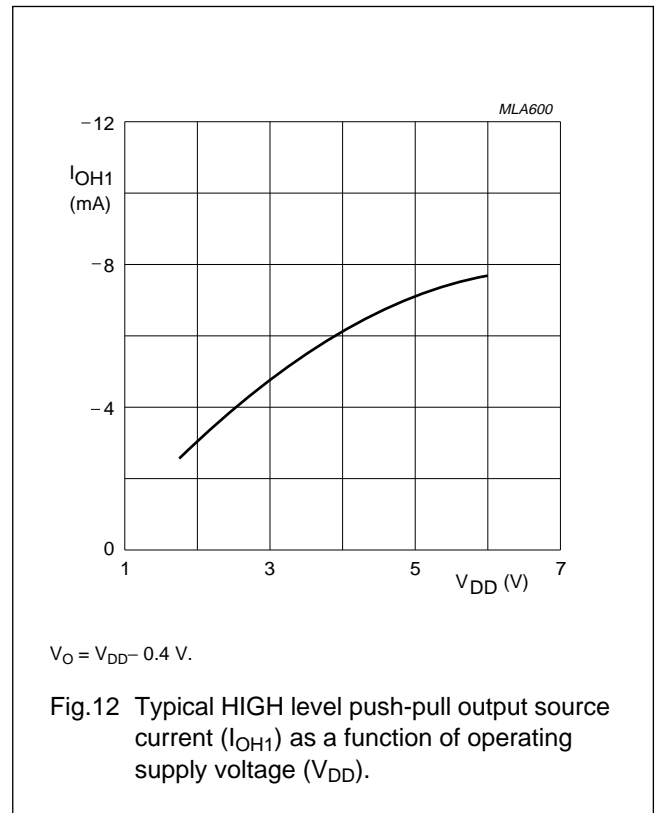
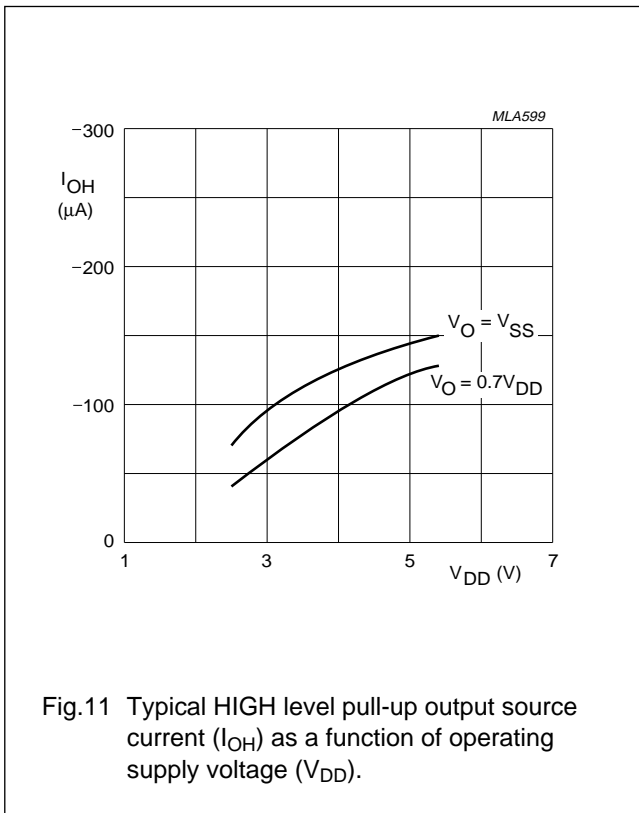
Microcontroller with extended I/O

PCF84C85A



Microcontroller with extended I/O

PCF84C85A



## Microcontroller with extended I/O

## PCF84C85A

**13 AC CHARACTERISTICS**

$V_{DD} = 2.5$  to  $5.5$  V;  $V_{SS} = 0$  V;  $T_{amb} = -40$  to  $+85$  °C; all voltages with respect to  $V_{SS}$ ; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$t_r$	rise time all outputs	$V_{DD} = 5$ V; $T_{amb} = 25$ °C; $C_L = 50$ pF	–	30	–	ns
$t_f$	fall time all outputs	$V_{DD} = 5$ V; $T_{amb} = 25$ °C; $C_L = 50$ pF	–	30	–	ns
$f_{xtal}$	clock frequency	see Fig.3	1	–	16	MHz

**Table 4** I<sup>2</sup>C-bus timing (see Figs 14 and 15)

SYMBOL	PARAMETER	INPUT (see Fig.14)	OUTPUT (see Fig.15; note 1)
<b>SCLK</b>			
$t_{HD;STA}$	START condition hold time	$\geq \frac{14}{f_{xtal}}$	$\frac{DF + 9}{2 \times f_{xtal}}$
$t_{LOW}$	SCLK LOW time	$\geq \frac{17}{f_{xtal}}$	$\frac{DF - 3}{2 \times f_{xtal}}$ ; note 2
$t_{HIGH}$	SCLK HIGH time	$\geq \frac{17}{f_{xtal}}$	$\frac{DF + 3}{2 \times f_{xtal}}$ ; note 2
$t_{RC}$	SCLK rise time	$\leq 1$ $\mu$ s	$\leq 1$ $\mu$ s; note 3
$t_{FC}$	SCLK fall time	$\leq 0.3$ $\mu$ s	$\leq 0.1$ $\mu$ s; note 4
<b>SDA</b>			
$t_{BUF}$	bus free time	$\geq \frac{14}{f_{xtal}}$	$\geq 4.7$ $\mu$ s; note 5
$t_{SU;DAT}$	data set-up time	$\geq 250$ ns	$\geq \frac{15}{f_{xtal}}$ ; note 6
$t_{HD;DAT}$	data hold time	$\geq 0$	$\geq \frac{9}{f_{xtal}}$
$t_{RD}$	SDA/P2.3 rise time	$\leq 1$ $\mu$ s	$\leq 1$ $\mu$ s; note 3
$t_{FD}$	SDA/P2.3 fall time	$\leq 0.3$ $\mu$ s	$\leq 0.1$ $\mu$ s; note 4
$t_{SU;STO}$	STOP condition set-up time	$\geq \frac{14}{f_{xtal}}$	$\frac{DF - 3}{2 \times f_{xtal}}$

**Notes**

1. DF stands for Division Factor: the divisor of  $f_{xtal}$  (see "PCF84CXXXA family" data sheet).

2. Values given for ASC = 0; for ASC = 1:  $t_{HIGH} = \frac{3(DF + 1)}{4 \times f_{xtal}}$ ;  $t_{LOW} = \frac{DF - 3}{4 \times f_{xtal}}$

3. Determined by I<sup>2</sup>C-bus capacitance ( $C_b$ ) and external pull-up resistor.

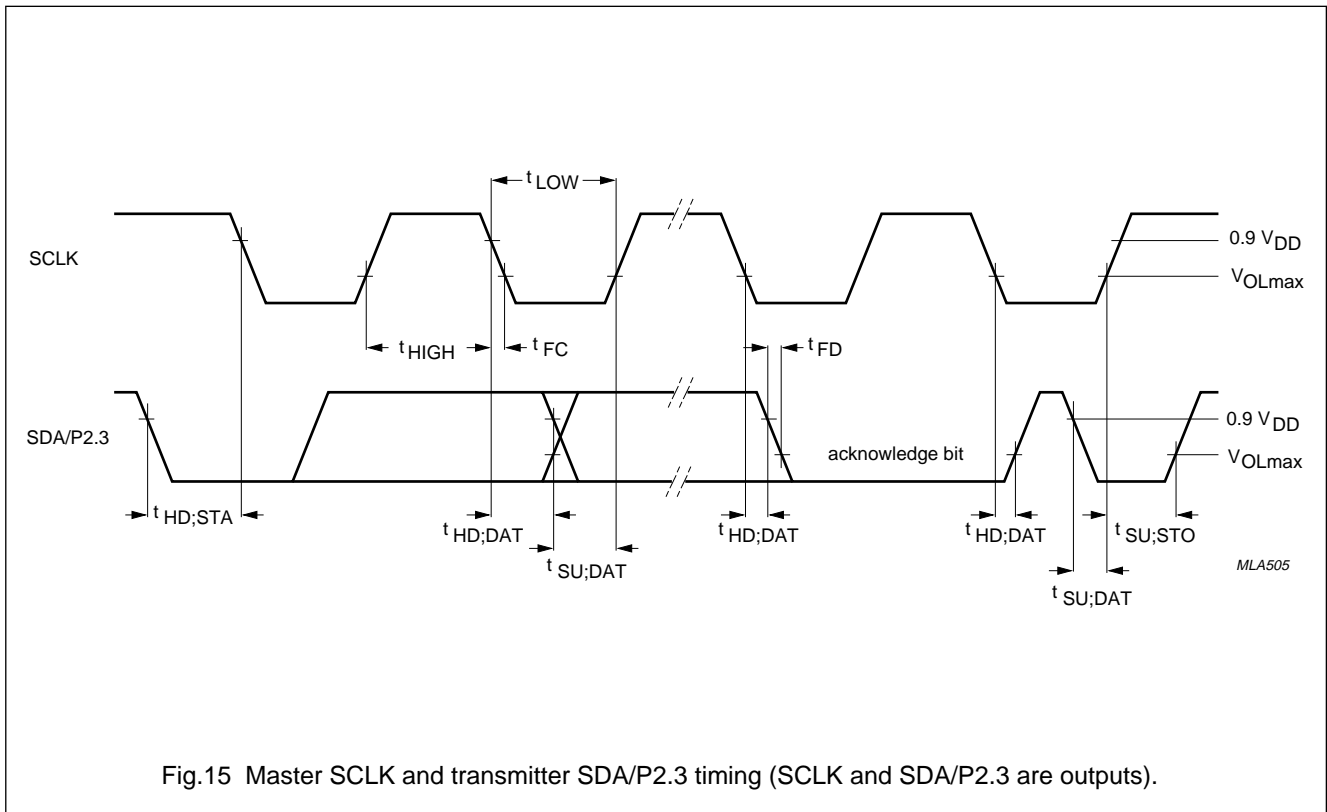
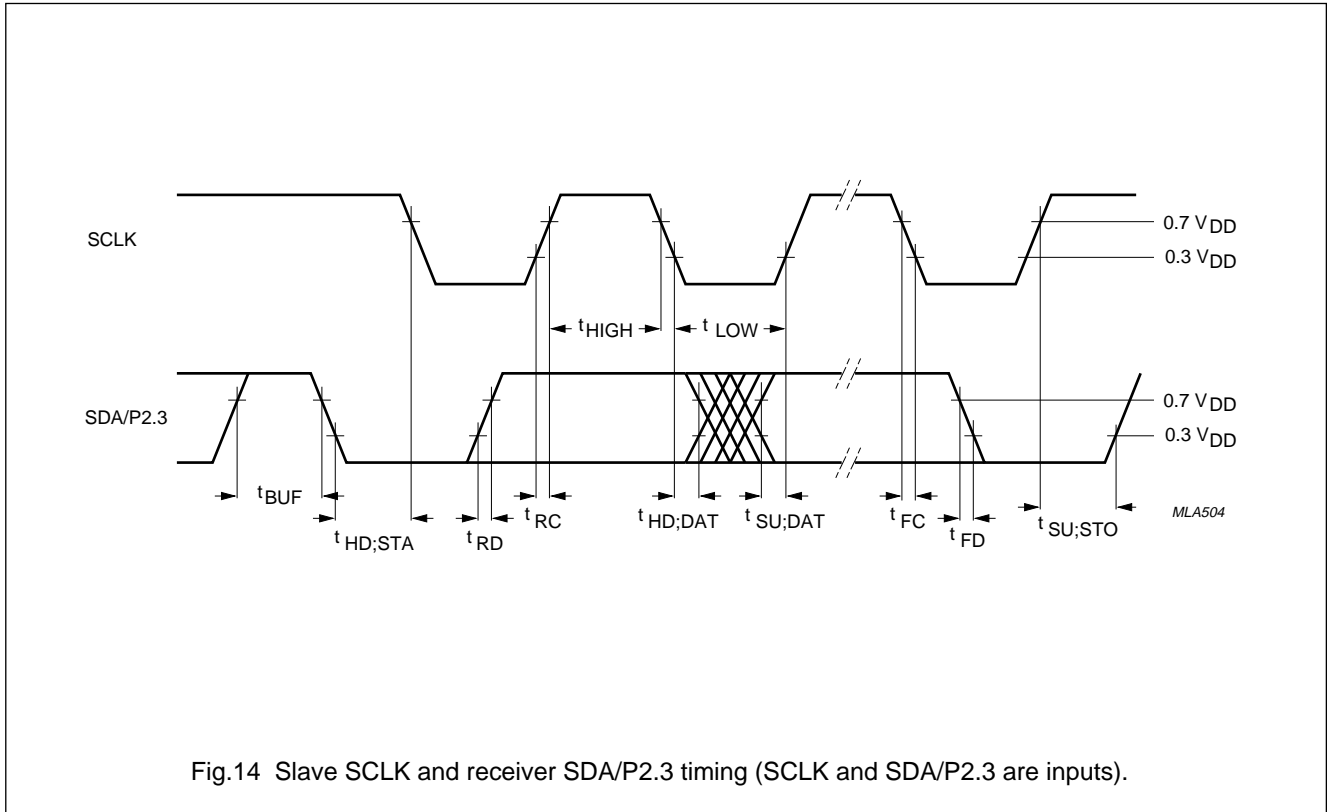
4. At maximum allowed I<sup>2</sup>C-bus capacitance  $C_b = 400$  pF.

5. Determined by program.

6. If  $t_{LOW} < \frac{24}{f_{xtal}}$ ,  $t_{SU;DAT} \geq \frac{t_{LOW} - 9}{f_{xtal}}$ , independent of ASC.

Microcontroller with extended I/O

PCF84C85A



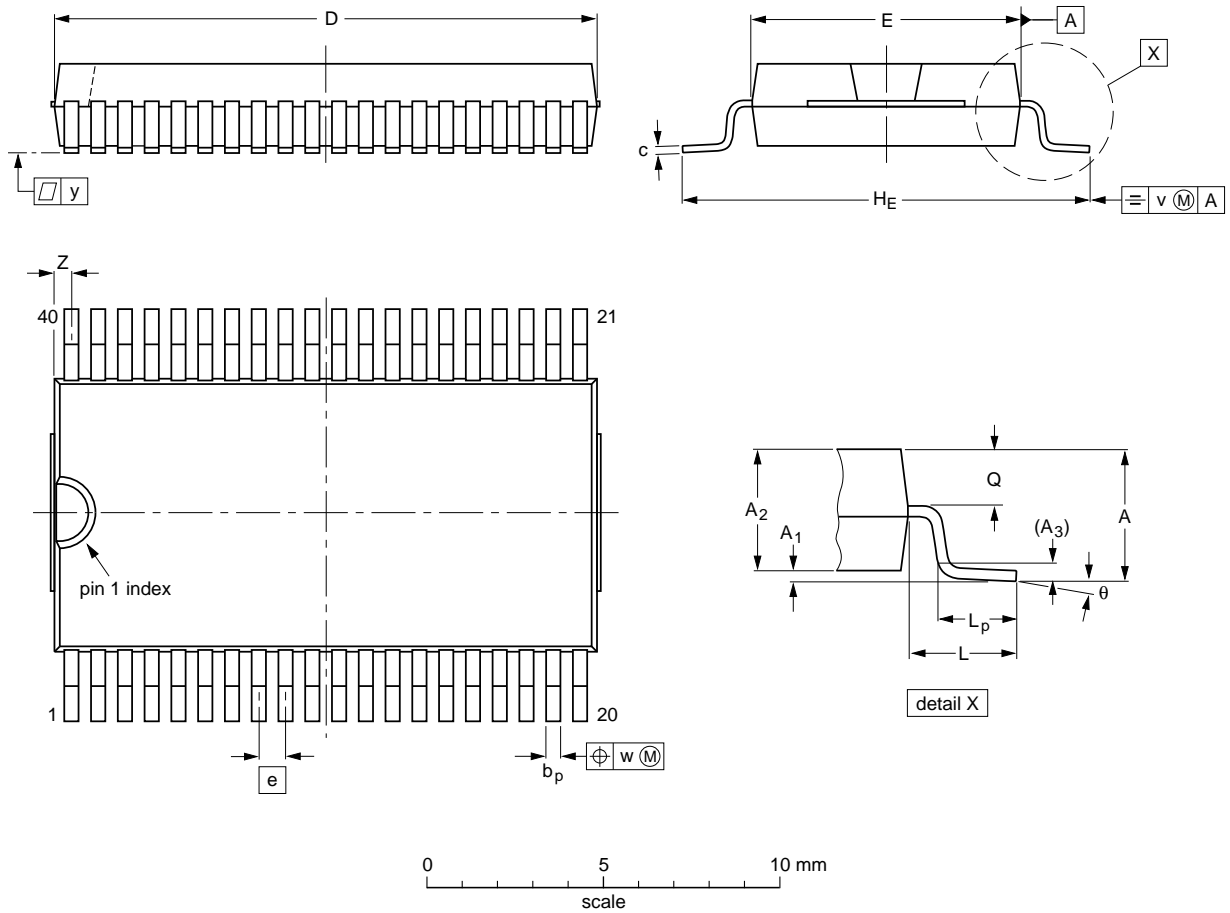
Microcontroller with extended I/O

PCF84C85A

14 PACKAGE OUTLINES

VSO40: plastic very small outline package; 40 leads

SOT158-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.70	0.3 0.1	2.45 2.25	0.25	0.42 0.30	0.22 0.14	15.6 15.2	7.6 7.5	0.762	12.3 11.8	2.25	1.7 1.5	1.15 1.05	0.2	0.1	0.1	0.6 0.3	7° 0°
inches	0.11	0.012 0.004	0.096 0.089	0.010	0.017 0.012	0.0087 0.0055	0.61 0.60	0.30 0.29	0.03	0.48 0.46	0.089	0.067 0.059	0.045 0.041	0.008	0.004	0.004	0.024 0.012	

Notes

1. Plastic or metal protrusions of 0.4 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

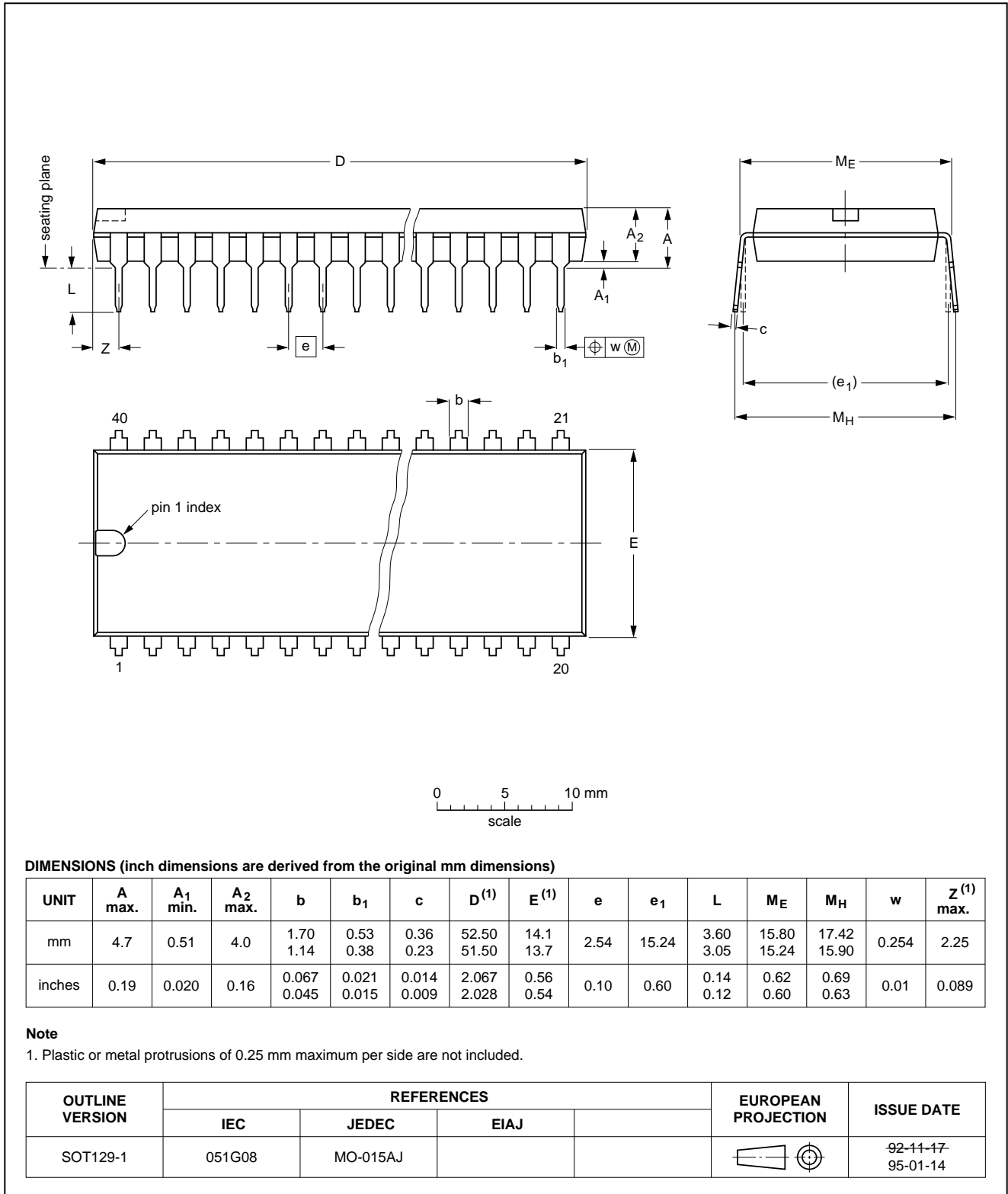
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT158-1						92-11-17 95-01-24

Microcontroller with extended I/O

PCF84C85A

DIP40: plastic dual in-line package; 40 leads (600 mil)

SOT129-1



## Microcontroller with extended I/O

## PCF84C85A

### 15 SOLDERING

#### 15.1 Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

#### 15.2 DIP

##### 15.2.1 SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ( $T_{stg\ max}$ ). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

##### 15.2.2 REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

#### 15.3 SO and VSO

##### 15.3.1 REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO and VSO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

##### 15.3.2 WAVE SOLDERING

Wave soldering techniques can be used for all SO and VSO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

##### 15.3.3 REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.



## Microcontroller with extended I/O

## PCF84C85A

**16 DEFINITIONS**

<b>Data sheet status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	

**17 LIFE SUPPORT APPLICATIONS**

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

**18 PURCHASE OF PHILIPS I<sup>2</sup>C COMPONENTS**

Purchase of Philips I<sup>2</sup>C components conveys a license under the Philips' I<sup>2</sup>C patent to use the components in the I<sup>2</sup>C system provided the system conforms to the I<sup>2</sup>C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.